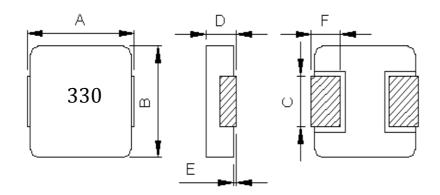


1. Features

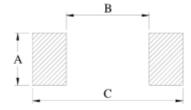
- 1. Magnetic metal powder inductor.
- 2. Compact design.
- 3. High current \cdot low DCR \cdot high efficiency.
- 4. Very low acoustic noise and very low leakage flux noise.
- 5. High reliability.
- 6. 100% Lead(Pb)-Free and RoHS compliant.

2. Dimensions (外形尺寸)



编号		A	В	С	D	Е	F
尺寸(mm	1)	14.40Max.	12.80±0.30	4.00±0.50	6.50Max.	0~0.15	2.50±0.50

3. Recommend Land Pattern Dimensions (推荐焊盘)



A	4.50
В	3.40
С	14.10

Unit: mm

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SLO1365H330MTT

4. Specifications

	L0	L0 DCR (mΩ)				
Part Number	Inductance (μΗ)			Heat Rating Current DC Amps. Idc (A)	Saturation Current DC Amps. Isat (A)	
	@ (0A)	Тур.	Max	. ()		
SL01365H330MTT	33	40	48	5.0	9.0	

NOTES:

- 1. Idc: DC current (A) that will cause an approximate $\triangle T$ of $40^{\circ}C$,
- 2. 2. Isat: DC current (A) that will cause Lo to drop approximately 35%
- 3. All test data is referenced to 25°C ambient
- 4. Operating Temperature Range -55°C to +125°C
- 5. The part temperature (ambient + temp rise) should not exceed 125 °C under the worst operating conditions. Circuit design,

component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature.

Part temperature should be verified in the end application.

- 6. TEST FREQUENCY:100KHz,1.0V
- 7. TESTING INSTRUMENT L :Agilent4284A,WK4235,CH3302/G LCR METER CH1320.CH1320S BIAS CURRENT SOURCE

Rdc:CH502BC MICRO OHMMETER

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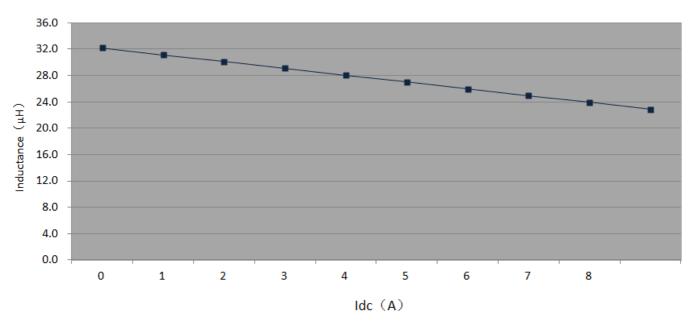
5. TEST REPORT

			TEST REPORT	ı		
		Ele	ctrical Characteri	istic		
			Item			
		LOA	DCR	I rms		I sat
Specification	on	33uH	$48m\Omega$	5Amps		9Amps
Tolerance	! :	±20%	Max	∆T≦40°C		L≧65%
1		32. 1	40. 1	35. 3℃ 71.		
2		30.8	39.8			
3		31. 4	40. 2			
4		31. 7	39. 9			
5		32	40.4			
6		31.6	40. 2			71. 22%
7		32. 2	40. 4			
8		31.6	40. 1			
9		32. 4	40.3			
10		31. 3	40.2			
\overline{X}		31.71	40.160			
			External Dimens	ions		
			Item			
	A	В	С	D	F	
Specification	14.4	12.8	4.0	6.5	2.5	
Tolerance	Max (mm)	± 0.3(mm)	± 0.5(mm)	Max (mm)	$\pm 0.5 (mm)$)
1	14.07	12.75	4.03	6.37	2.59	
2	14.08	12.74	4.02	6.34	2.64	
3	14.13	12.75	4.02	6.31	2.59	
4	14.12	12.74	4.03	6.26	2.59	
5	14.07	12.75	4.03	6.34	2.61	
6	14.12	12.75	4.02	6.35	2.63	
7	14.09	12.74	4.01	6.36	2.61	
8	14.11	12.75	4.01	6.29	2.63	
9	14.08	12.75	4.01	6.29	2.61	
10	14.12	12.75	3.99	6.32	2.61	
\overline{X}	14.099	12.747	4.017	6.323	2.611	

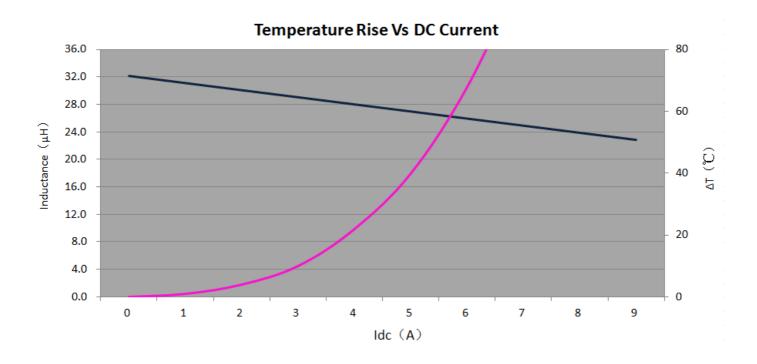


6. INDUCTANCE VS DC CURRENT





7.TEMPERATURE RISE VS DC CURRENT





SLO1365H330MTT

8. Reliability and Test Condition

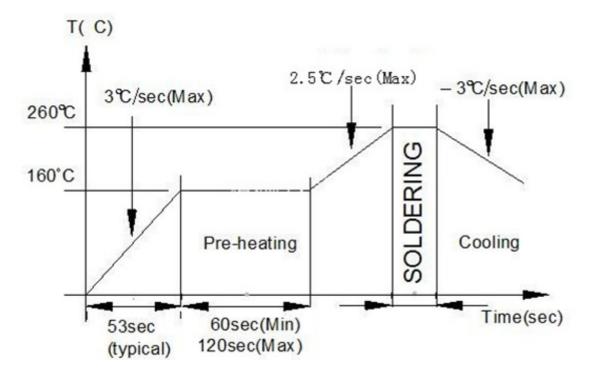
Item	Performance	Test Condition		
Operating temperature	-40~+125°C			
Storage temperature	-10~+40°C,50~60%RH (Product without taping)			
Electrical Performance Tes	t			
Inductance		HP4284A,CH11025,CH3302,CH1320,CH1320S		
DCR	Refer to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.		
Saturation Current (Isat)	△L30% typical.	Saturation DC Current (Isat) will cause L0 to drop △L(%)(keep quickly).		
Heat Rated Current (Irms)		Heat Rated Current (Irms) will cause the coil		
Heat Rated Current (Irms)	Approximately △T≦40°C	temperature rise _AT(°C) without core loss.		
Reliability Test				
High Temperature Exposure		Temperature:125±2°C		
Test		Duration:1000±12hrs		
Low Temperature LifeTest		Temperature:-40±2°C		
Low Temperature LifeTest	-	Humidity:85±3%RH.		
Biased Humidity Test		Temperature:85±2°C Duration:1000±12hr		
,		S.		
		Condition for 1 cycle		
Thermal shock test		Step1:-40+0 / -2°C 15±1 min.		
Thermal shock test	Electric specifications should be satisfied	Step2:Room temperature within ≦0.2		
	†	Frequency: 10-2000-10Hz for 20 min.		
Nile and an Acad		Amplitude: Parts mounted within 2" from any secure		
Vibration test		point. Directions and times: X, Y,Z directions for 20		
Reflow test	-	min. Pre-heat: 150±5°C		
Reflow test		Duration : 5		
		minutes Temperature : 260±5°C ⋅ 20~40		
		After dip into flux · dip into		
Solder test	Terminals should be covered by over 95% solder on visual inspection	solder 235±5°C · 4±1seconds Flux · solder for lead free		
00,000 1631	Tommado onodia do covered by over 30 /6 solder on visual mapection	(ANSI /J-STD-002C Method		

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9. SOLDERING CONDITION RECOMMENDED

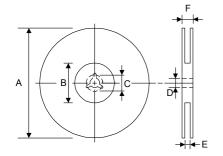
- 9.1 器件焊接方式:回流焊
- 9.1.1 回流焊焊接方式及推荐炉温曲线



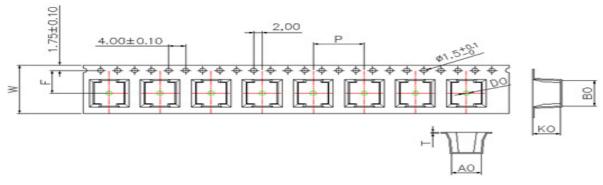
- 9.1.2 高温耐热性描述(在 265℃的熔融铅料中,停留时间不少于 10 秒,3 次最少,无质量问题。)
- 9.1.3 返修温度和时间(温度: 400℃; 时间: 不少于5秒。)
- 9.1.4 焊接次数 (元器件能承受的焊接次数不少于 3 次。)

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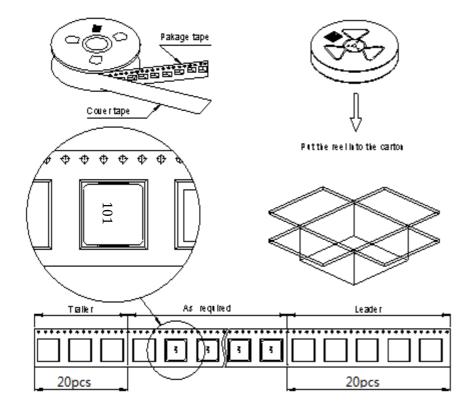
10. Packaging Information



ТҮРЕ	A	В	С	D	Е	F
24mm	330	100	21.0±0.8	$13\frac{+0.5}{-0.2}$	16±0.3	26.4



Q'TY (PCS)	A0	В0	КО	W	Р	Т
500	14.5±0.1	12.9±0.1	6.6±0.1	24.0±0.3	16.0±0.1	0.40±0.05



- ①一卷包装:500Pcs;
- ② 小箱装两卷:一共1000Pcs;
- ③ 大箱装三小箱:一共3000Pcs.